

# HT5010 Thermal Conductive Gap Filler

## BENEFITS AND FEATURES

- High thermal performance
- Low contact resistance
- Easily dispensable and reworkable
- High compressibility for low stress applications
- Reliable thermal performance
- Anti-crack and dripping
- Anti-blocking and abrasion

## OVERVIEW

Honeywell HT5010 one-part Gap Filler provides an effective thermal properties and high conformability with its high compressibility. It is formulated to deliver high dispense rates for improved productivity, long-term reliability performance and easy reworkable. It is designed to minimize thermal resistance at interfaces, maintain excellent performance through reliability testing.

## TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications equipment
- Automotive electronics
- Power supplies & semiconductors
- Memory & power modules
- Power electronics

## STORAGE & USE

- Shelf life 12 months at 0-35°C,  
≤65% RH

Property	HT5010	Test Method
Feature	Silicone-based	-
	Pre-cured	-
Color	Grey	Visual
Thermal Conductivity (W/m-K)	5.0	ASTM D5470
Thermal Impedance (°C-In <sup>2</sup> /W) (1mm@10psi, Typical Value)	0.28	ASTM D5470
Dispense Rate (g/min)	>14	90psi 30cc EFD syringe
Density(g/cm <sup>3</sup> )	3.4	ASTM D792
Minimum BLT (µm)	140	HON Internal
Volatile Content (TML%)	<0.05	HON Internal
Volatile Content (CVCM%)	<0.02	HON Internal
Dielectric Strength (KV/mm)	8	ASTM D149
Flammability Rating	V-0(Equivalent)	UL 94
Operating Temperature (°C)	-40~150	HON Internal

\*Typical property data values should not be used as specifications

## Honeywell Electronic Materials

USA: 1-509-252-2102  
 China: 400-840-2233  
 Germany: 49-5137-999-9199  
 Japan: 81-3-6730-7092  
 Korea: 82-2-3483-5076  
 Singapore: 65-6580-3593

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